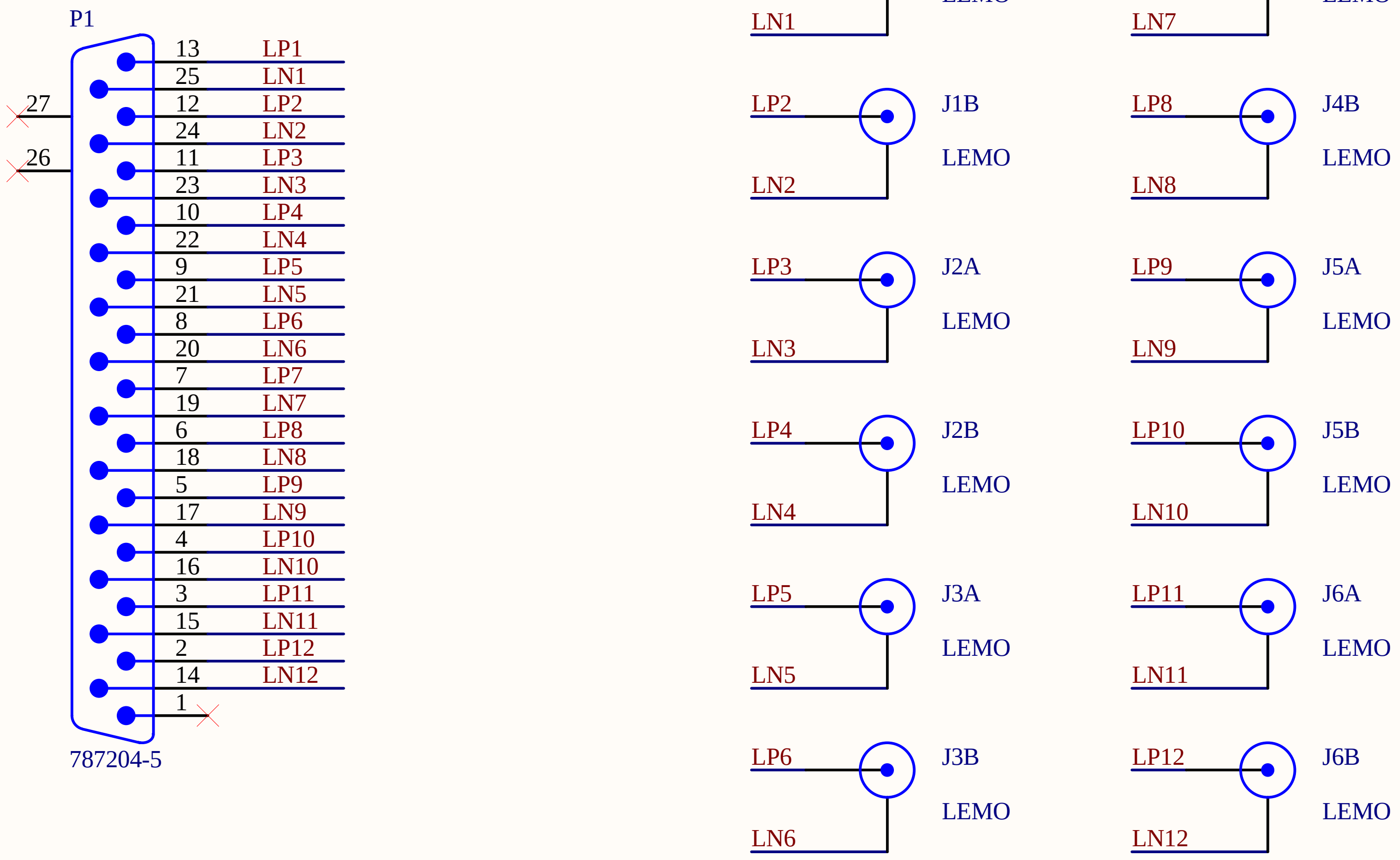
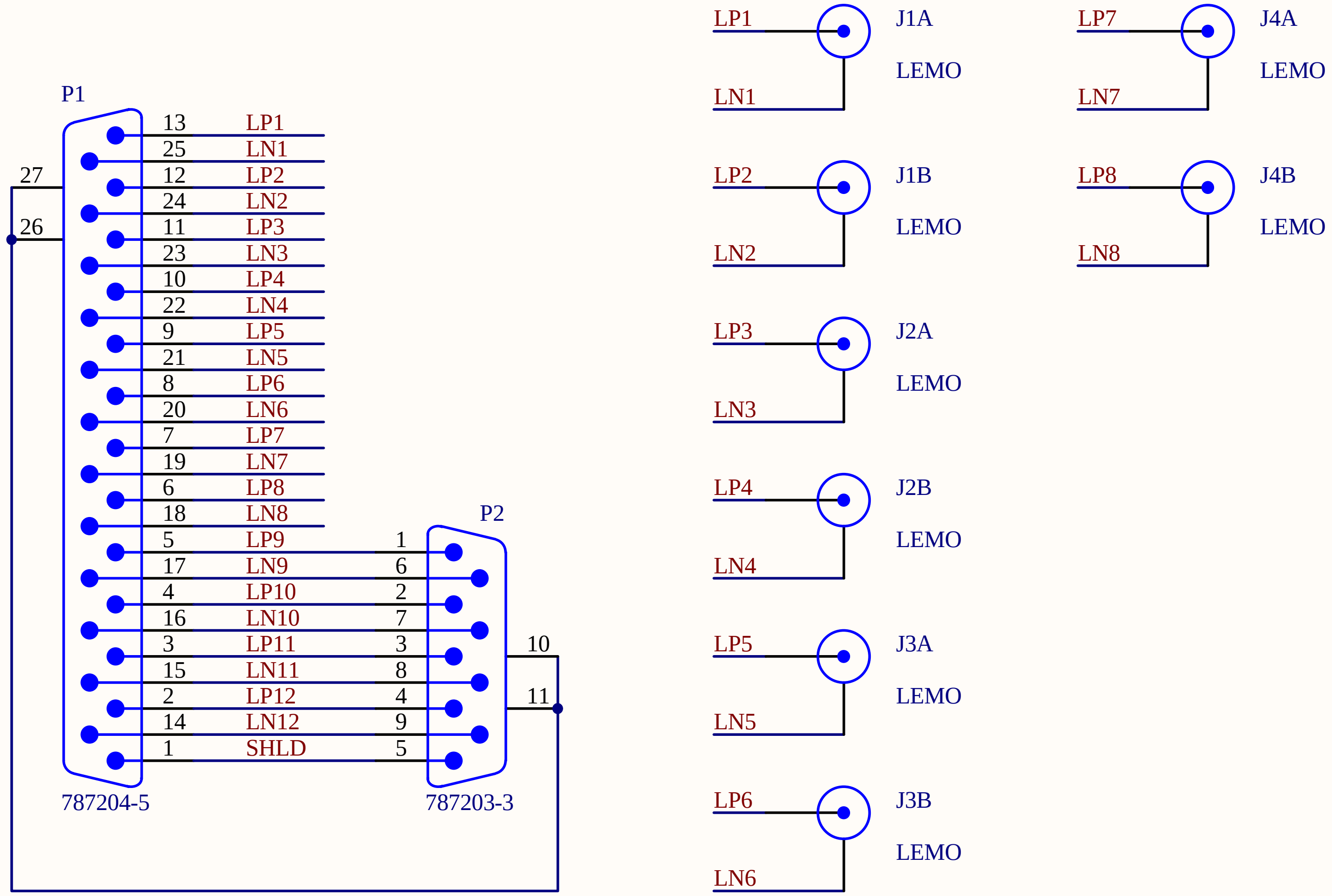


Assembly Instructions (ultra high vacuum compatibility):
- board material is Rogers RT/Duroid 6002 or Rogers RO3003
- no silk screen, no solder mask
- gold plating of top and bottom layer

Parts:
- P1 is ERNI 204478 or 154214 (insulator material must be LCP)
- J1 through J6 are LEMO EPY.00.250.NTN (insluator material is teflon)

The grounds of the dual LEMOs are connected, ie., LN1 and LN2 are the same

| Title | **In-Vacuum LEMO Adapter** | | |
|---|---|---|---|
| Size<br>A | Number<br>D060191-A | | Revision<br>A |
| Date: | 8/9/2006 | Sheet 1 of 3 | |
| File: | C:\Users\..\LEMOAdapter.SchDoc | Drawn By: | Daniel Sigg |



Assembly Instructions (ultra high vacuum compatibility):
- board material is Rogers RT/Duroid 6002 or Rogers RO3003
- no silk screen, no solder mask
- gold plating of top and bottom layer

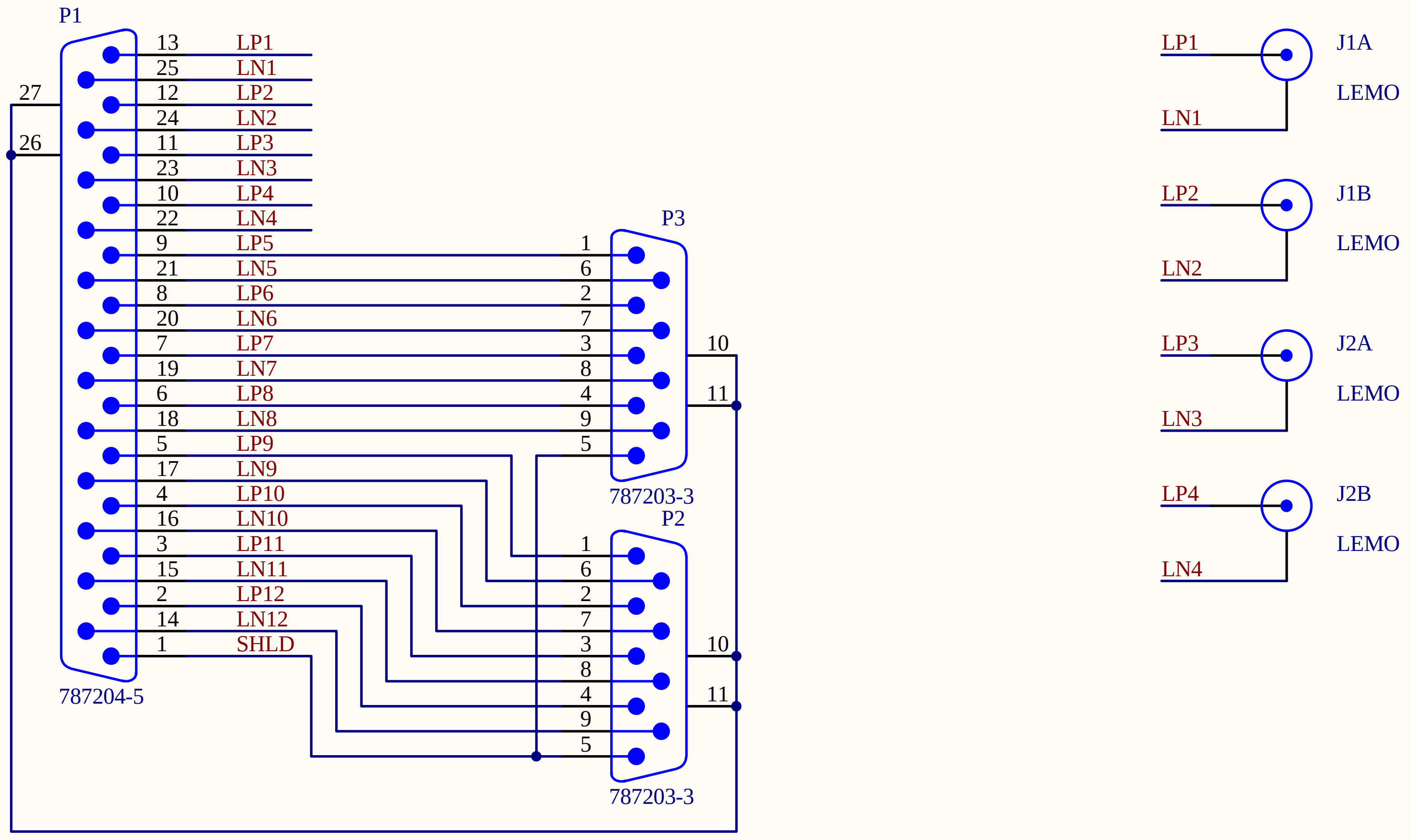
Parts:
- P1 is ERNI 204478 or 154214 (insulator material must be LCP)
- P2 is ERNI 204466 or 154206  (insulator material must be LCP)
- J1 through J6 are LEMO EPY.00.250.NTN (insluator material is teflon)

The grounds of the dual LEMOs are connected, ie., LN1 and LN2 are the same

Title
**In-Vacuum LEMO Adapter Alternate**

| Size | Number | Revision |
|---|---|---|
| A | D060191-A | A |

Date: 8/9/2006
Sheet 2 of 3
File: C:\Users\..\LEMOAdapterAlt.SchDoc
Drawn By: Daniel Sigg



Assembly Instructions (ultra high vacuum compatibility):
- board material is Rogers RT/Duroid 6002 or Rogers RO3003
- no silk screen, no solder mask
- gold plating of top and bottom layer

Parts:
- P1 is ERNI 204478 or 154214 (insulator material must be LCP)
- P2/P3 are ERNI 204466 or 154206  (insulator material must be LCP)
- J1 through J6 are LEMO EPY.00.250.NTN (insluator material is teflon)

The grounds of the dual LEMOs are connected, ie., LN1 and LN2 are the same

Title **In-Vacuum LEMO Adapter Alt 2**

| Size | Number | Revision |
|---|---|---|
| A | D060191-A | A |

Date: 8/9/2006
Sheet 3 of 3
File: C:\Users\..\LEMOAdapterAlt2.SchDoc
Drawn By: Daniel Sigg